



1. Features of AH4724 Series:

- · Ferrite based SMD inductor with lower core loss.
- Inductance range: 180.0 nH to 365.0 nH, custom values are welcomed.
- High current output chokes up to 95.0 Amp with approx. 20% roll off.
- · Low profile 6.0mm Max. height.
- 12.1 x 10.0 mm Foot Print.
- Ideal for Buck Converter, VRM & High Density Board Design.
- Operating frequency of up to 5.0MHz.
- Operating temperature range of -55° C to + 130° C. RoHS & HF compliant.
- T & R Qty's: 500pcs, 13" Reel.

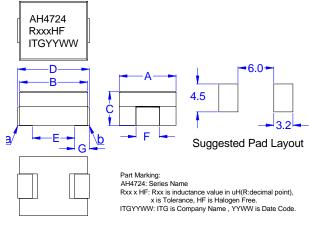


2. Electrical Characteristics of AH4724 Series:

	OCL 1	DCR ³	Isat1 ⁴	Isat2 ⁴	Isat3 ⁴	Irms ⁵
ITG Part Number	(nH)	(mΩ)	(A)	(A)	(A)	(A)
	± 10% or 15%	± 7.0%	@25℃	@45 ℃	@100℃	@25 ℃
AH4724-R18KHF	180.00 ,10%	0.48	60.00	58.00	52.00	40.00
AH4724-R21KHF	215.00 ,10%	0.48	54.00	50.00	47.00	40.00
AH4724-R23KHF	230.00 ,10%	0.48	47.00	45.00	42.00	40.00
AH4724-R32KHF	325.00 ,10%	0.48	32.00	31.00	29.00	40.00
AH4724-R36LHF	365.00 ,15%	0.48	30.00	29.00	27.00	40.00

3. Mechanical Dimension of AH4724 Series:

Α	В	С	D	E	F	G
Max.	Max.	Max.	Max.	Nom.	Nom.	Nom.
10.00	11.70	6.00	12.10	7.00	3.80	2.30



Third Angle Projection:



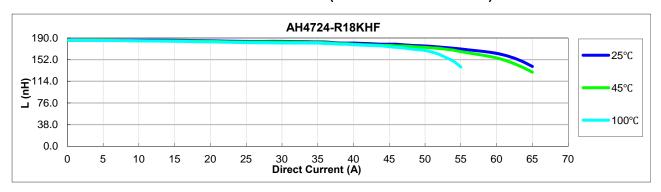
Notes:

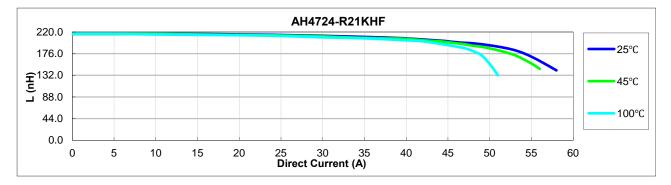
- 1. Open Circuit Inductance (OCL) test condition: 500KHz,0.25Vrms,0Adc at 25°C.
- 2. L @ Isat and L @ Irms Test condition: 500KHz,0.25Vrms (Ta=25°C).
- 3. The nominal DCR is measured from point "a" to point "b", as shown above on the mechanical drawing (Ta=25°C).
- 4. Isat1, Isat2 & Isat3: DC current that will cause inductance to drop approximately by 20%.
- 5. Irms: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout,trace thickness and width,air-flow and proximity of other heat generating components will affect the temperature rise.
- 6. It is recommended the part temperature not exceed 130° C under worst case operating conditions as verified in the end application.
 - New York 1 914 347 2474 Taipei 886 2 2698 8669 Kaohsiung 886 7 350 2275
- Japan 81 568 85 2830 Shenzhen 86 755 8418 6263 Shanghai 86 21 5424 5141 Hong Kong 852 9688 9767
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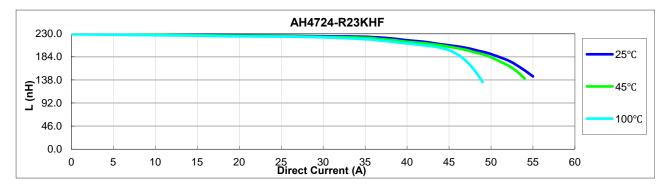


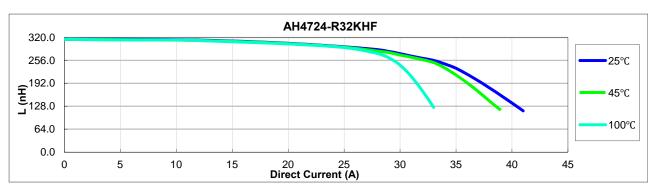


4. Inductance Characteristics of AH4724 Series (Inductance vs Current):









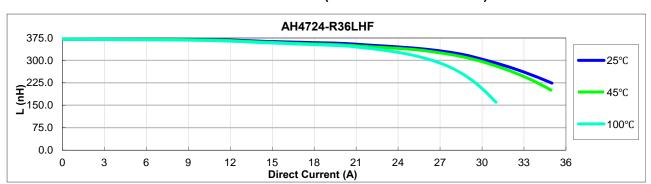
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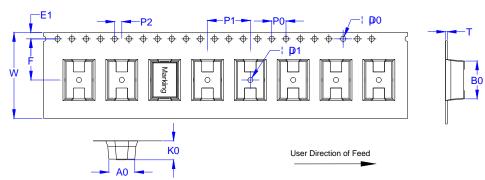






6.PACKAGE SPECIFICATION.(UNIT:mm):

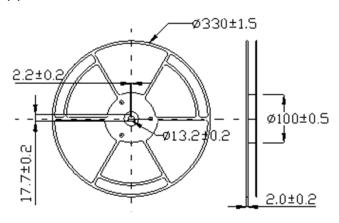
(1).ENCAPSOLATION MODE:



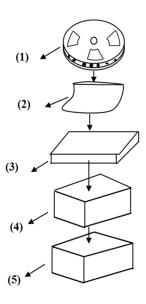
(2).DIMENSION(mm):

w	Α0	В0	K0	P1	P0	P2	D0	D1	F	E1	Т
24.0+0.3/-0.1	10.2±0.1	12.3±0.10	6.20±0.10	16.0±0.10	4.00±0.10	2.00±0.10	1.50+0.10/-0	1.50+0.10/-0	11.5±0.10	1.75±0.10	0.40±0.05

(3).REEL SIZE:



(4).PACKAGE MODE:



(5).PACKAGING LIST:

No.	Packing Part	Dimension (mm)	Material	Quantity
1	Reel	330	Plastic	500Pcs/Reel
2	Bag	450x360x0.075	Plastic	1Reel/Bag
3	Small Box	340X335X45	Paper	1Bag/Small Box
4	Middle Box	356X350X226	Paper	4Small Boxes/Middle Box
5	Outer Box	378X362X252	Paper	1Middle Box/Outer Box

- (6).WEIGHT: N.W: 2.95 g/pcs (APPROX), TOTAL 5.95 Kg(APPROX), G.W:TOTAL 8.90Kg (APPROX).
- (7).Storage conditions: -40°C~85°C ,75%RH (Max.).
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7.RELIABILITY TEST:

TEST ITEMS	SPECIFICATIONS	TEST METHOD AND REMARKS		
		According to IEC68-2-20.		
		1. Soldering temperature:245±5°C		
Solder ability	The electrodes shall be at least 90% covered with new solder coating	2. Solder:99.3Sn/0.7Cu		
	with new solder coating	3. Flux:Rosin		
		4. Immersion time:5±1Sec		
		1. Preheat temperature150°C.		
		2. Preheat time:1min		
Soldering heat		3. Solder temperature260±5°C		
resistance	Inductance change:within±10%of initial value	4. Dipping time:10±1Sec		
		5. Measured at room temperature after placing		
		for 24hours		
		According to MIL-STD-202 Method 204.		
	1. Appearance:no damage	1.Frequency:10 to 55Hz.		
Vibration(OUT LAB)	All Electrical and mechanical parameters within tolerance	2.Amplitude:1.52mm		
	Within tolerance	3.Direction and timeX Y and Z		
		Direction for 2 hours each		
		According to IEC68-2-1MethodCa:		
	E. 7 in Electrical and mechanical parameters	1. Temp:40±2°C		
Ulara Salta a sa		2. Humidity:90%-95%RH		
Humidity resistance test		3. Test time:500 \pm 2H		
		4. The component should be stabilized at		
		normal condition for24 Hours before test		
		According to IEC68-2-2.		
	Appearance: no damage	1. 1. Temperature:85±3°C		
High temperature resistance test	All Electrical and mechanical parameters within telegrapes.	2. Test time:500+24H		
resistance test		3. The component should be stabilized at		
		normal condition for 24hours before test		
		According to IEC68-2-1 Method A(Ad).		
	1. Appearance: no damage	1. Temperature:-40±3°C		
Low Temperature resistance test		2. Test time:500+24H		
resistance test	within tolerance	3. The component should be stabilized at		
		normal condition for 24hours before test		
Temperature cycles test	Appearance: no damage All Electrical and mechanical parameters	According to IEC68-2-14 Method N(Nb).		
		1. High-temp:85 ± 3 duration:30 min		
		2. room -temp:25±2°CDuration3H		
		3. Low-temp:-40±3Duration30min		
		4. room-temp: 25±2°CDuration3H		
	313.3.13	5. Number of cycle:10cycles		
		6. The component should be stabilized at		
		normal condition for 24hours before test		

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Soldering Reflow Chart

